Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company name* Company unique ID Unique ID Authority Description Contact Name Title - Contact Title - Contact Title - Contact Title - Compliance NA Product Enviro Compliance NA Product-Env-Stewards NA Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Namufacturing Site Weight* UOM Version Manufacturing Site Weight* UOM Version Manufacturing Site Weight* UOM Version Manufacturing Process Information Vanufacturing Process Information Vanufacturing Process Information Vanufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matter Tin (Sn) - annealed CU Alloy 1 260 © 30 seconds 3	752-21.1											als and Mfg	Informati	ion	
Inter Name Title - Contact Product Env-Stewards Inter - Contact Product Env-Stewards Inter - Compliance Inter - Compliance Inter - Compliance Inter - Contact Product Env-Stewards Inter - Compliance Inter - Contact Inter -	upplier Informa	ation										_			
Title - Contact Name Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance NA Product Enviro Stewards © onsemi.com NA Na unifacturing Site Veight* UOM U Na unifacturing Proccess Information NA Naunifacturing Proccess Information NA Naunifacturing Site Veight* UOM U Naunifacturing Proccess Information Naunifacturing Proccess Information Naunifacturing Proccess Information Naunifacturing Proccess Information Na unifacturing Site Naunifacturing Naunifacturing Site Naunifacturing Naunifacturing Site Naunifacturing Naunifacturi	Company name* Company unique ID					J	Unique ID Authority				Response Date*				
Product-Env-Stewards	nsemi											2023-06-0	8		
Authorized Representative* Product-Env-Stewards Requester Item Number Mfr Item Number M	Contact Name			Title - Conta	ct		I	Phone - Conta	ıct*			Email - C	ontact*		
Product Envi-Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM UMAnufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 1 Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM UM UM Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds 3 Comments	Product-Env-Stewar	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative* Ti				Title - Representative			Phone - Representative*			Email - Representative*				
CM1223-02SR 2 CH. ESD W/BACKDRIVE 2023-06-08 CN1 10.87 mg E Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles	Product-Env-Stewar	ds	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	e Version	n N	Manufacturing Site	W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments			CM1223-	-02SR	2 CH. ESD W/BAC	CKDRIVE		2023-06-08		C	CN1	10).87	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 omments				arminal Paga	Alloy	STD 020 MSI	Dating	Dook Proc	ooss Pody	Comporative	May Time at Peak	Tomporatus	o Numb	per of Poflow Cya	los
Comments					Alloy J-	31D-020 MSL	Rating		cess body	Т,				ber of Reflow Cyc	ies
	•	(Sii) - aimealeu		U Anoy	1			400		IC	30	seconds	5 3		
ver 1 - maximum time at peak temperature uni mg soldering is 10-50 seconds		no at noak tamporeture d	lunina asla	doring is 10 2	0 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.09	mg	Supplier	Silicon (Si)	7440-21-3		0.09	mg
Lead Frame	3.47	mg	Supplier	Silver (Ag)	7440-22-4		0.0357	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0326	mg
			Supplier	Iron (Fe)	7439-89-6		0.0812	mg
			Supplier	Copper (Cu)	7440-50-8		3.3173	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0031	mg
Mold Compound-Black	6.91	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.691	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0345	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.0019	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.4915	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.691	mg
Plating	0.38	mg	Supplier	Tin (Sn)	7440-31-5		0.38	mg
Wire Bond - Au	0.02	mg	Supplier	Gold (Au)	7440-57-5		0.02	mg